Title (en)

SYSTEM AND METHOD OF CLEANING AND ETCHING A SUBSTRATE

Title (de)

SYSTEM UND VERFAHREN ZUM REINIGEN UND ÄTZEN EINES SUBSTRATS

Title (fr)

SYSTEME ET PROCEDE DE NETTOYAGE ET DE GRAVURE D'UN SUBSTRAT

Publication

EP 1782461 A4 20080528 (EN)

Application

EP 05762857 A 20050623

Priority

- US 2005022172 W 20050623
- US 88000704 A 20040628

Abstract (en)

[origin: WO2006012174A2] One embodiment provides a method of processing a substrate. The method includes applying a solution to a surface of a substrate. At least one reacting species has been produced by dissociation of the solution by applying energy such as a light to the solution. A first material on the substrate is reacted and removing the reacted first material. A system for processing a substrate is also described.

IPC 8 full level

H01L 21/461 (2006.01); **B08B 7/04** (2006.01); **C23C 14/00** (2006.01); **H01L 27/01** (2006.01)

CPC (source: EP KR)

H01L 21/304 (2013.01 - KR); **H01L 21/31133** (2013.01 - EP); **H01L 21/461** (2013.01 - KR); **H01L 21/6708** (2013.01 - EP)

Citation (search report)

- [X] US 6533902 B1 20030318 - MIKI NOBUHIRO [JP], et al & SILICON CARBIDE 2002 - MATERIALS, PROCESSING AND DEVICES. SYMPOSIUM 2-4 DEC. 2002 BOSTON, MA, USA, 2003, Silicon Carbide 2002 - Materials, Processing and Devices. Symposium (Mater. Res. Soc. Symposium Proceedings Vol.742) Mater. Res. Soc Warrendale, PA, USA, pages 271 - 276
- [X] DATABASE INSPEC [online] THE INSTITUTION OF ELECTRICAL ENGINEERS, STEVENAGE, GB; 2003, SASAKI D ET AL: "Photo-chemical pattern etching of silicon-carbide by using excimer laser and hydrogen peroxide solution", XP002476854, Database accession no. 7839009
- See references of WO 2006012174A2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

WO 2006012174 A2 20060202; **WO 2006012174 A3 20060914**; CN 101006571 A 20070725; EP 1782461 A2 20070509; EP 1782461 A4 20080528; JP 2008504714 A 20080214; KR 20070026687 A 20070308; TW 200608478 A 20060301; TW I271793 B 20070121

DOCDB simple family (application)

US 2005022172 W 20050623; CN 200580028522 A 20050623; EP 05762857 A 20050623; JP 2007519288 A 20050623; KR 20067027743 A 20061228; TW 94121622 A 20050628